

Glass Passivated Bridge Rectifiers

FEATURES

- Glass passivated junction
- Ideal for printed circuit board
- High case dielectric strength
- Typical IR less than 0.1µA
- High surge current capability
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition





KBU



MECHANICAL DATA

Case: KBU

Molding compound, UL flammability classification rating 94V-0

Base P/N with suffix "G" on packing code - green compound (halogen-free)

Terminal: Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test **Mounting torque:** 0.56 Nm max. **Weight:** 7.2 g (approximately)

PARAMETER	SYMBOL	KBU	KBU	KBU	KBU	KBU	KBU	KBU	Unit
PARAMETER	STWIBOL	401G	402G	403G	404G	405G	406G	407G	
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}			•	4				Α
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	150						А	
Rating for fusing (t<8.3ms)	l ² t				93				A ² s
Maximum instantaneous forward voltage (Note 1) I _F = 2A I _F = 4A	V _F				1.0 1.1				V
Maximum DC reverse current $T_J=25$ °C at rated DC blocking voltage $T_J=125$ °C	I _R				5 500				μΑ
Typical junction capacitance per leg	Cj				240				pF
Typical thermal resistance	$R_{ heta JC} \ R_{ heta JA}$	4 19						°C/W	
Operating junction temperature range	TJ			-	55 to +15	50			°С
Storage temperature range	T _{STG}			-	55 to +15	50			°С

Note 1: Pulse Test with PW=300µs, 1% Duty Cycle

Note 2: Measured at 1MHz and applied Reverse Voltage of 4.0V D.C.



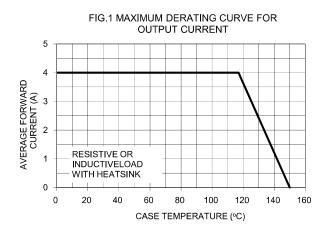
ORDERING INFORMATION						
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
KBU40xG (Note 1)	ТО	G	KBU	500 / Tray		

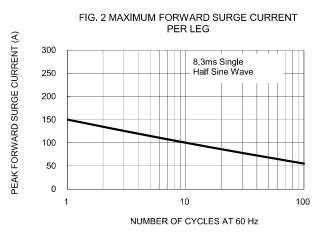
Note 1: "x" defines voltage from 50V (KBU401G) to 1000V (KBU407G)

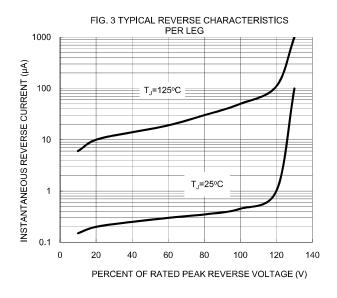
EXAMPLE							
PREFERRED P/N PART N		PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION			
KBU407G T0	KBU407G	T0					
KBU407G T0G	KBU407G	T0	G	Green compound			

RATINGS AND CHARACTERISTICS CURVES

(TA=25°C unless otherwise noted)







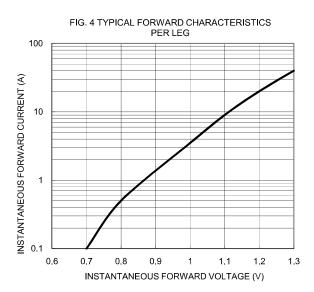
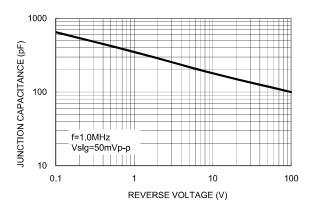
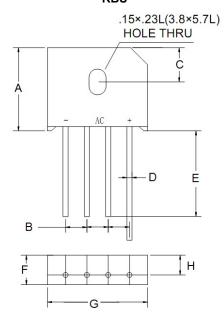




FIG. 5 TYPICAL JUNCTION CAPACITANCE



PACKAGE OUTLINE DIMENSIONS KBU



DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	18.8	19.8	0.740	0.780	
В	4.6	5.6	0.181	0.220	
С	8.2 (TYP.)	0.322 (TYP.)		
D	1.2	1.3	0.047	0.051	
Е	20.0	-	0.787	-	
F	6.8	7.1	0.268	0.280	
G	22.7	23.7	0.894	0.933	
Н	4.6	5.0	0.181	0.197	

MARKING DIAGRAM



P/N = Specific Device Code G = Green Compound

YWW = Date Code F = Factory Code

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